



US 20230230945A1

(19) **United States**

(12) **Patent Application Publication**  
**CHUANG**

(10) **Pub. No.: US 2023/0230945 A1**

(43) **Pub. Date: Jul. 20, 2023**

(54) **PACKAGE STRUCTURE AND METHOD FOR FORMING SAME**

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(21) Appl. No.: **17/656,104**

(22) Filed: **Mar. 23, 2022**

(30) **Foreign Application Priority Data**

Jan. 20, 2022 (CN) ..... 202210066315.0

**Publication Classification**

(51) **Int. Cl.**  
**H01L 23/00** (2006.01)  
**H01L 25/10** (2006.01)

(52) **U.S. Cl.**  
CPC ..... **H01L 24/08** (2013.01); **H01L 24/03** (2013.01); **H01L 24/05** (2013.01); **H01L 24/06** (2013.01); **H01L 24/09** (2013.01); **H01L 24/16**

(2013.01); **H01L 24/80** (2013.01); **H01L 25/105** (2013.01); **H01L 2224/09505** (2013.01); **H01L 2224/05688** (2013.01); **H01L 24/13** (2013.01); **H01L 2224/13147** (2013.01); **H01L 2224/16146** (2013.01); **H01L 2224/06505** (2013.01); **H01L 2224/0603** (2013.01); **H01L 2224/06051** (2013.01); **H01L 2224/05541** (2013.01); **H01L 2224/05557** (2013.01); **H01L 2224/03614** (2013.01); **H01L 2224/0345** (2013.01); **H01L 2224/03452** (2013.01); **H01L 2224/08148** (2013.01); **H01L 2224/80948** (2013.01); **H01L 2224/80097** (2013.01); **H01L 2224/80895** (2013.01); **H01L 2224/80896** (2013.01); **H01L 2924/1436** (2013.01); **H01L 2924/1431** (2013.01); **H01L 2225/1058** (2013.01)

(57)

**ABSTRACT**

A package structure includes the following: a logic die; and a plurality of core dies sequentially stacked on the logic die along a vertical direction, in which the plurality of core dies include a first core die and a second core die interconnected through a hybrid bonding member; the hybrid bonding member includes: a first contact pad located on a surface of the first core die; and a second contact pad located on a surface of the second core die; the first contact pad is in contact bonding with the second contact pad.

